Operating	Applicat	ole s	tandard										
Rating Description and process Description Descripti	Operating				-40 °C to +105°C (N	Note1)					-10 °C to +60°C (No		1
Personal processor DF65-48-1.7C Internally Paragonal Processor DF65-48-1.7C Internally Paragonal Processor DF65-48-1.7C Internally Paragonal Processor DF65-48-1.7C Internal Processor DF65-48-	Operating		ange	\ / Ien									
Applicable content DF85-2428SCF(**) DF85-2428S	Raung				DF65-4S-1.7C			idity range Rating Voltage			AC 50 V		
Voltage SO VACIO Current 24 MVIG 4 A SA WIG 25 A SA WIG 2			•				⊢ ∧ `						
Current 24 AWG : 2.5 A 26 28 AWG : 2.5		Ve			` ')		oting \	/oltage		26-28 AWG : 3.5 A		
Specifications Test method Requirements C Construction General examination Visually and by measuring instrument. According to drawing. Confirmed visually. Confirmed visually. Contract Resistance Initialized lavel method Insulation resistance Insulation resi					55 1 1 157 = 5							Α	
Item	Curterit			26 AWG : 2.5 A				9\					
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General examination Visually and by measuring instrument. According to drawing.		Item			Test method					Req	uirements	QT	АТ
Electric characteristics Contact resistance 20mV MAX, 1mA(DC or 1000Hz). 10mΩ MAX. 2modamage, crack or looseness of parts. 2modamage, cr	Construction												,
Electric characteristics Contact Resistance Ilom Q MAX. Ilom Q MAX.			-				According to drawing.				X	X	
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millivoit level method Insulation resistance 100 V DC. 100 MΩ MIN. No flashover or breakdown. 100 MΩ MIN. 2No damage, crack or looseness of parts. 100 MΩ MIN. 2No damage, crack or looseness of parts. 100 MΩ MIN. 2No damage, crack or looseness of parts. 100 MΩ MIN. 2No damage, crack or looseness of parts. 100 MΩ MIN. 2No damage, crack or looseness of parts. 100 MΩ MIN. 2No damage, crack or looseness of parts. 100 MΩ MIN. 2No damage, crack or looseness of parts. 100 MΩ MIN. 2No damage, crack or looseness of parts. 100 MΩ MIN. 2No damage, crack or looseness of parts. 100 MΩ MIN. 2No damage, crack or looseness of parts. 100 MΩ MIN. 2No damage, crack or looseness of parts. 100 MΩ MIN. 2No damage, crack or looseness of parts. 100 MΩ MIN. 2No damage, crack or looseness of parts. 100 MΩ MIN. 2No damage, crack or looseness of parts. 100 MΩ MIN. 2No damage, crack or looseness of parts. 100 MΩ MIN. 2No damage, crack or looseness of parts. 100 MΩ MIN. 2No damage, crack or looseness of parts. 100 MΩ MIN. 2NO damage, crack or looseness of parts. 100 MΩ MIN. 2NO damage, crack or looseness of parts. 100 MΩ MIN. 2NO damage, crack or looseness of parts. 100 MΩ MIN. 2NO damage, crack or looseness of parts. 100 MΩ MIN. 2NO damage, crack or looseness of parts. 100 MΩ MIN. 2NO damage, crack or looseness of parts. 100 MΩ MIN. 2NO damage, crack or looseness of parts. 100 MΩ MIN. 2NO damage, crack or looseness of parts. 100 MΩ MIN. 2NO damage, crack or looseness of parts. 100 MΩ MIN. 2NO damage, crack or looseness of parts. 100 MΩ MIN. 2NO damage, crack or looseness of parts. 100 MΩ MIN. 2NO damage, crack or looseness of parts. 100 MΩ MIN. 2NO damage, crack or looseness of parts. 100 MΩ MIN. 2NO damage, crack or looseness of parts. 100 MΩ MIN. 2NO damage, crack or looseness of parts. 100 MΩ MIN. 2NO damag												1	
Insulation resistance 100 V DC. Voltage proof 500 V AC for 1 min. Mechanical characteristics Mechanical operation 30 times insertion and extraction. 20 Contact resistance: 20mΩ MAX. 21 No damage, crack or looseness of parts. Vibration Frequency 10 to 55 Hz, single amplitude 0,75 mm, at 10 cycles for 3 direction. Shock 490 m/s² duration of pulse 11 ms at 3 times each for 3 both axial directions. Environmental characteristics Bampheat (Steady state) (After leaving the room temperature for 1 - 2h.) Rapid change of Temperature -55°C → +85°C Time 30min → 30min Under 5 cycles. (The transferring time of the tank is 2 - 3 min) (After leaving the room temperature for 1 - 2h.) Resistance to soldering heat 1) Reflow soldering heat No deformation of case of excessive looseness of the terminals. No deformation of case of excessive looseness of the terminals. No deformation of case of excessive looseness of the terminals. No deformation of case of excessive looseness of the terminals. Soldering irine: 3s No strength on contact. Soldering time: 3s No strength on contact. Soldered at solder temperature, 246°C for in immersion, duration, 5s. Soldering irine: 3s Nostered to the condition of long term storage for unused products before mounted on PCB. After mounted on PCB, operation temperature and humidity range are applied for interim storage during transportation. Count Description of revisions Designed Checked DISH-00004782 SN MINA Approved K.I. AKIYAMA 2 Checked OIL MIYAM070 20				ZUMV MAX, 1mA(DC or 1000Hz).				10mΩ MAX.				X	_
Voltage proof 500 V AC for 1 min. No flashover or breakdown.				100 V DC.				100 MΩ MIN.				X	_
Mechanical characteristics Mechanical operation 30 times insertion and extraction. 30 times insertion and extraction. (□)Contact resistance: 20mΩ MAX. ②No damage, crack or looseness of parts. ↑ No electrical discontinuity of 1μs. ②No damage, crack or looseness of parts. ↑ No electrical discontinuity of 1μs. ②No damage, crack or looseness of parts. ↑ No electrical discontinuity of 1μs. ②No damage, crack or looseness of parts. ↑ No electrical discontinuity of 1μs. ②No damage, crack or looseness of parts. ↑ No electrical discontinuity of 1μs. ②No damage, crack or looseness of parts. ↑ No damage, crack or looseness of parts. ↑ The part of the part of 1 - 2h. ↑ The part of 1 - 2h. ↑ The part of 1 - 2h. ↑ Time ↑ Soyles. ↑ Time ↑ Soyles. ↑ Time ↑ Soyles. ↑ Time ↑ Soyles. ↑ The transferring time of the tank is 2 - 3 min) ↑ (After leaving the room temperature for 1 - 2h.) ↑ No damage, crack or looseness of parts. ↑ No damage, crack or l				500 V AC for 1 min.				No flashover or breakdown.				X	<u> </u>
Mechanical operation 30 times insertion and extraction. ⊕ Contact resistance: 20mΩ MAX. ②No damage, crack or looseness of parts.			charact										1
Comparison Frequency 10 to 55 Hz, single amplitude O.75 mm, at 10 cycles for 3 direction. O.75 mm, at 10 cycles for 1 cycles. O.75 mm, at 10 cyc					insertion and extraction.		100	Conta	act resist	ance	: 20mΩ MAX.	X	_
O.75 mm, at 10 cycles for 3 direction. 2 No damage, crack or looseness of parts.	Meenamear operation							0 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1					
Shock 490 m/s² duration of pulse 11 ms at 3 times each for 3 both axial directions.	Vibration							· ·				Х	_
Substance to soldering September Se	Shock												-
Environmental characteristics Damp heat (Steady state) (After leaving the room temperature for 1 - 2h.) Rapid change of Time 30min→30min Under 5 cycles. (The transferring time of the tank is 2 - 3 min) (After leaving the room temperature for 1 - 2h.) Resistance to soldering heat Resistance to soldering heat Reflow with some part time with some part time for 1 - 2h.) Resistance to soldering heat Resistance to soldering heat Reflow time with some part tim												X	_
Damp heat (Steady state) (After leaving the room temperature for 1 - 2h.) (2 Insulation resistance: 20mΩ MAX (2 Insulat	Environr	nent	al charac									ı	<u> </u>
Rapid change of temperature Temperature -55°C → +85°C Time 30min → 30min Under 5 cycles. (The transferring time of the tank is 2 - 3 min) (After leaving the room temperature for 1 - 2h.) Resistance to soldering heat 1) Reflow soldering (*Reflow time *) Number of reflow cycles : 2 cycles max. Duration above 220°C, 60sec. max. Peak temperature: 250°C 10 sec. max. Pere-heat time *> Pre-heat time *> Pre-heat time(min) : 90 sec. Pre-heat time(max) : 120 sec. 2) Manual soldering Soldering iron tempreture: 350±10°C, Soldering time: 3s No strength on contact. Soldered at solder temperature, 245°C for in immersion, duration, 5s. Note 1: Include the temperature rising by current. Note 2: No condensing Note 3: Apply to the condition of long term storage for unused products before mounted on PCB. After mounted on PCB, operation temperature and humidity range are applied for interim storage during transportation. Papproved K1. AKIYAMA 22 Remarks Approved K1. AKIYAMA 22 Checked 0M. MIYAM0T0 26 Designed T1. OHSAKO 21 Unless otherwise specified, refer to IEC 60512.					at 40 ± 2°C , 90 to 95 %, 96	6 h.	100	Conta	act resist	ance	: 20mΩ MAX.	X	Ι –
Time 30min—30min Under 5 cycles. (The transferring time of the tank is 2 - 3 min) (After leaving the room temperature for 1 - 2h.) Resistance to soldering heat 1, Reflow soldering Nefflow soldering Number of reflow cycles : 2 cycles max. Duration above 220°C, 60sec. max. Peak temperature: 250°C 10 sec. max. Peak temperature (min): 150°C Pre-heat time? Pre-heat time(min): 90 sec. Pre-heat time(min): 90 sec. Pre-heat time(max): 120 sec. 2) Manual soldering Soldering iron tempreture: 350±10°C, Soldering iron tempreture: 350±10°C, Soldering time: 3s No strength on contact. Solderability Soldered at solder temperature, and in the temperature rising by current. Note 2: No condensing Note 3: Apply to the condition of long term storage for unused products before mounted on PCB. After mounted on PCB, operation temperature and humidity range are applied for interim storage during transportation. Count Description of revisions Designed Checked Approved K1. AKIYAMA 22 Checked 0M. MIYAMOTO 20 Designed T1. OHSAKO 20 Drawn T1. OHSAK				(After leaving the room temperature for 1 - 2h.)				~					
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The transferring time of the tank is 2 - 3 min) (After leaving the room temperature for 1 - 2h.) The transferring time of the tank is 2 - 3 min) (After leaving the room temperature for 1 - 2h.)	temperature			Under 5 cycles. (The transferring time of the tank is 2 - 3 min)									
A new uniform coating of solder shall cover minimum of 95% of the surface being immersed. A new uniform coating of solder shall cover minimum of 95% of the surface being immersed. A new uniform coating of solder shall cover mounted on PCB. After mounted on PCB, operation temperature and humidity range are applied for interims torage during transportation. Description of revisions Designed Tt. OHSAKO 24													
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Number of reflow cycles : 2 cycles max. Duration above 220°C, 60sec. max. Peak temperature : 250°C 10 sec. max. Peak temperature : 250°C 10 sec. max. 《Pre-heat time》 Pre-heat temperature((min) : 150°C Pre-heat temperature((max) : 180°C Pre-heat time((max) : 120 sec. 2) Manual soldering Soldering iron tempreture: 350±10°C, Soldering iron tempreture: 350±10°C, Soldering time: 3s No strength on contact. Solderability Soldered at solder temperature, 245°C for in immersion, duration, 5s. Note 1: Include the temperature rising by current. Note 2: No condensing Note 3: Apply to the condition of long term storage for unused products before mounted on PCB. After mounted on PCB, operation temperature and humidity range are applied for interim storage during transportation. Count Description of revisions Designed Checked Approved K1. AK1YAMIA 20 Checked 0M. M1YAM010 20 Designed TT. 0HSAKO 20 Unless otherwise specified, refer to IEC 60512.	Resistance to soldering			1) Reflow soldering				· · · · · · · · · · · · · · · · · · ·					_
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Peak temperature : 250°C 10 sec. max. ≪ Pre-heat time≫ Pre-heat temperature(min) : 150°C Pre-heat temperature(max) : 180°C Pre-heat time(min) : 90 sec. Pre-heat time(min) : 90 sec. Pre-heat time(max) : 120 sec. 2) Manual soldering Soldering iron temperature; 350±10°C, Soldering iron temperature, Solderability Soldered at solder temperature, 245°C for in immersion, duration, 5s. Note 1: Include the temperature rising by current. Note 2: No condensing Note 3: Apply to the condition of long term storage for unused products before mounted on PCB. After mounted on PCB, operation temperature and humidity range are applied for interim storage during transportation. Count Description of revisions Designed Checked 2 DIS-H-00004782 SN. MIWA SZ. 0N0 20 Remarks Approved KI. AKIYAMA 20 Checked OM. MIYAM0TO 20 Designed TT. 0HSAKO 20 Unless otherwise specified, refer to IEC 60512.													
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Pre-heat timperature(max): 180°C Pre-heat time(min): 90 sec. Pre-heat time(max): 120 sec. 2) Manual soldering Soldering iron tempreture: 350±10°C, Soldering time: 3s No strength on contact. Soldered at solder temperature, 245°C for in immersion, duration, 5s. Note 1: Include the temperature rising by current. Note 2: No condensing Note 3: Apply to the condition of long term storage for unused products before mounted on PCB. After mounted on PCB, operation temperature and humidity range are applied for interim storage during transportation. Count Description of revisions Designed Checked DIS-H-00004782 SN. MIWA SZ. ONO 20 Remarks Approved KI. AKIYAMA 20 Checked OM. MIYAMIOTO 20 Designed TT. OHSAKO 20 Drawn TT. OHSAKO 20 Drawn TT. OHSAKO 20				≪Pre-heat time≫ Pre-heat temperature(min): 150°C Pre-heat temperature(max): 180°C Pre-heat time(min): 90 sec. Pre-heat time(max): 120 sec. 2) Manual soldering									
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Approved KI. AKIYAMA 20	Cou	unt		Descript	ion of revisions		Designed	jned			Checked		ate
Checked OM. MIYAMOTO 20	2 2			DIS-	DIS-H-00004782 SN. M						SZ. 0N0 2		90416
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Unless otherwise specified, refer to IEC 60512. Drawn TT. 0HSAK0 20								Designed		ed	OM. MIYAMOTO	KO 201401	
5104 05454 0										ed	TT. OHSAKO		
Note QT:Qualification Test AT:Assurance Test X:Applicable Test Drawing No. ELC4-351454-0	Unless ot	herw	ise specif	ied, refer to IEC 60512.						n	TT. OHSAKO	20140114	
3	Note QT:	:Quali	ification Te	est AT:Assurance Test X:Applicable Test			Dra	Drawing No.			ELC4-351454-01		
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HIROSE ELECTRIC CO., LTD. Code No. CL666-6006-0-21	11/	'	HIR	•	FOTDIO OO LTD		Code No	0.	CL	.666	6-6006-0-21	A	1/1